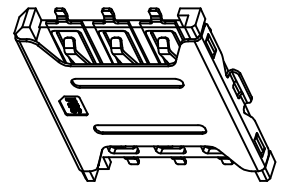
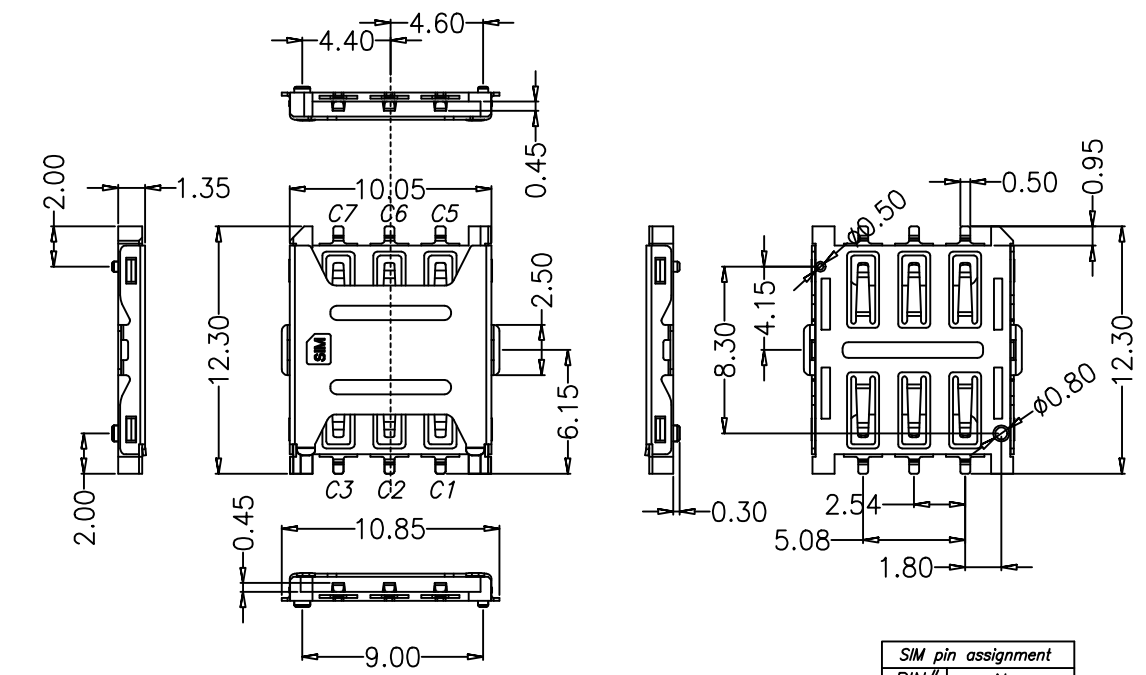


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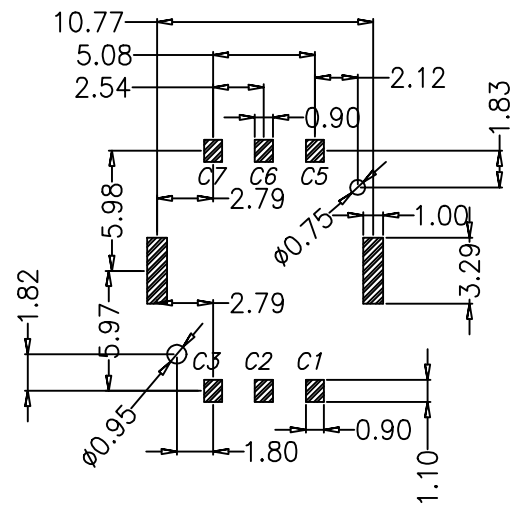
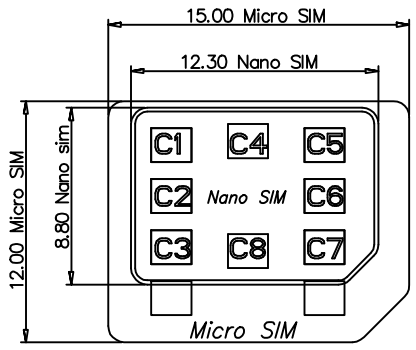
SIM pin assignment	
PIN#	Name
C1	VCC 供电电压
C2	RST 重置
C3	CLK 时钟
C5	GND 接地
C6	VPP 程序电压
C7	I/O 输入输出

**Specification**

**MATERIAL:**  
 Insulator: High Temperature Thermoplastic, UL 94V-0.  
 Contact: Cu210  
 SHEL: SWS

**PLATING:**  
 Contact: Plated 50u" Ni Overall Contact ALL Au 1U,  
 Shell: Plated 50u" Ni Overall, PAD Au 1U

**Electrical:**  
 Current Rating :0.5mA AC/DC max.  
 Voltage Rating :125V AC/DC  
 Ambient Temperature Range :-20° C~+60° C  
 Storage Temperature Range :-40° C~+70° C  
 Ambient Humidity Range :95% R.H. Max.  
 Contact Resistance:100mΩmax.  
 Insulation Resistance:1000MΩmin./500VDC  
 Mating Cycles:10,000 Insertions  
 Reflow peak temp.: 260° C ±5° C, 3" S  
 Mating Cycles:3,000 Insertions Min



GENERAL TOLERANCE		KINGCONN 皇海科技股份有限公司	
X± 0.50	X*± 5°	名称(TITLE) NAND-SIM 卡座 NO PUSH H1.35	
.X± 0.30	.X*± 2°		
.XX± 0.20	.XX*± 1°		
单位(UNIT) mm	料号(PART NO.) 7SIMC-F0-0030	图号(DWG NO.) 7SIMC-F0-0030	张数(SHEET) 1/1
审核(APPROVAL)	核数(CHECKED)	制图(DRAWN)	更改(REV) A